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# GOMACTech-20

“Microelectronics for a New Decade: Global Competition and Near-Peer Challenges”

Town & Country Resort & Convention Center, San Diego, CA  
16-19 March 2020

## First Call for Papers

GOMACTech was established primarily to report on developments in microcircuit technologies and applications for government systems. Created in 1968, the conference has focused on advances in systems and technologies being developed by the Department of Defense and other government agencies and has been used to announce major government microelectronics initiatives and to provide a forum for government reviews. GOMACTech-20 features plenary sessions addressing “Microelectronics for a New Decade: Global Competition and Near-Peer Challenges,” as well as, a technical program describing the latest technological advances in the field, including trustworthy components/technologies, electro-optical components, RF components, micro-nano electronics, electronics integration, electronics materials, emerging neuromorphic electronics, quantum information/sensing technologies and technologies beyond Moore’s Law, advances in wide and ultrawide-bandgap material and device development, and novel power-distribution architectures. Abstracts are solicited in the topic areas listed below. Detailed descriptions of the technical topic areas can be found [here](#). GOMACTech is the premier forum for reporting on government-funded microcircuit research and other research efforts that focus on the technology needs of government systems. It is an unclassified, export-controlled event. All registrants must provide proof of U.S. citizenship or permanent residence status and sign a non-disclosure statement prior to being permitted entry into the conference. Authors whose abstract is accepted (oral and poster presentations) are expected to produce a paper for the conference proceedings.

### Technical Topic Areas

Radiation-Hardened Technologies, Designs, and Systems

Trusted, Assured, and Cyber-Secure Microelectronics

RF Technologies, Components, and Systems

EO/IR Technologies, Components, and Systems

High-Performance Digital and Mixed-Signal Technologies

Photonic Technologies, Components, and Systems

Power Electronics and Emerging Power Technologies

Packaging, Integration, Thermal, and Control Technologies

Emerging Technologies (Quantum, Neuromorphic, Flexible Electronics, ICs beyond Moore’s Law...)

Advanced Materials and Processes

• Electronic Abstracts Due <a href="http://www.gomactech.net/">http://www.gomactech.net/</a>	September 13, 2019
• Author Notification of Acceptance	November 1, 2019
• Final Paper Due	January 10, 2020

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